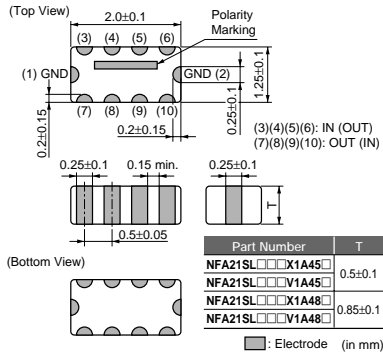


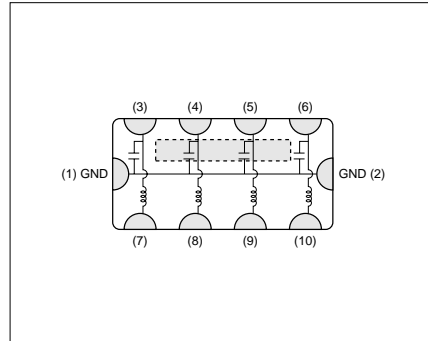
EMIFIL® (LC Combined) Array

NFA21SL_X Series (0805 Size)

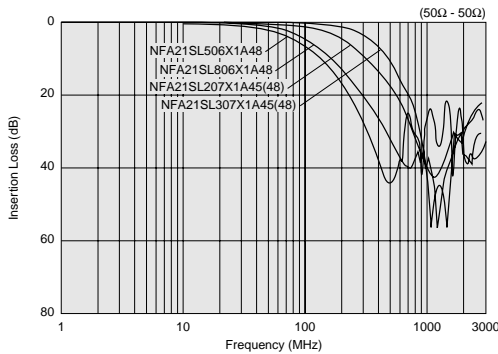
■ Dimensions



■ Equivalent Circuit



■ Insertion Loss Characteristics (Main Items)



■ Packaging

Code	Packaging	Minimum Quantity
L	180mm Embossed Tape	4000
B	Bulk(Bag)	1000

■ Rated Value (□: packaging code)

Part Number	Nominal Cut-off Frequency	Insertion Loss (Cut-off Frequency)	Insertion Loss (500MHz) (min.)	Insertion Loss (800MHz) (min.)	Insertion Loss (1000MHz) (min.)	Rated Voltage	Rated Current	Insulation Resistance (min.)	Withstand Voltage
NFA21SL207X1A45□	200MHz	2 to 7	13dB	25dB	25dB	10Vdc	100mA	1000M ohm	30Vdc
NFA21SL307X1A45□	300MHz	2 to 7	7dB	20dB	25dB	10Vdc	100mA	1000M ohm	30Vdc
NFA21SL506X1A48□	50MHz	0 to 6	30dB	-	20dB	10Vdc	20mA	1000M ohm	30Vdc
NFA21SL806X1A48□	80MHz	2 to 7	25dB	-	25dB	10Vdc	20mA	1000M ohm	30Vdc
NFA21SL207X1A48□	200MHz	2 to 7	13dB	25dB	25dB	10Vdc	100mA	1000M ohm	30Vdc
NFA21SL307X1A48□	300MHz	2 to 7	7dB	20dB	25dB	10Vdc	100mA	1000M ohm	30Vdc

Operating Temperature Range: -55°C to +125°C Number of Circuits: 4

Continued on the following page.

● This data sheet is applied for LC Combined CHIP EMIFIL® used for General Electronics equipment for your design.

⚠ Note:

1. This datasheet is downloaded from the website of Murata Manufacturing co., Ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.

 Continued from the preceding page.

■ Caution/Notice

Caution (Rating)

Do not use products beyond the rated current and rated voltage as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

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